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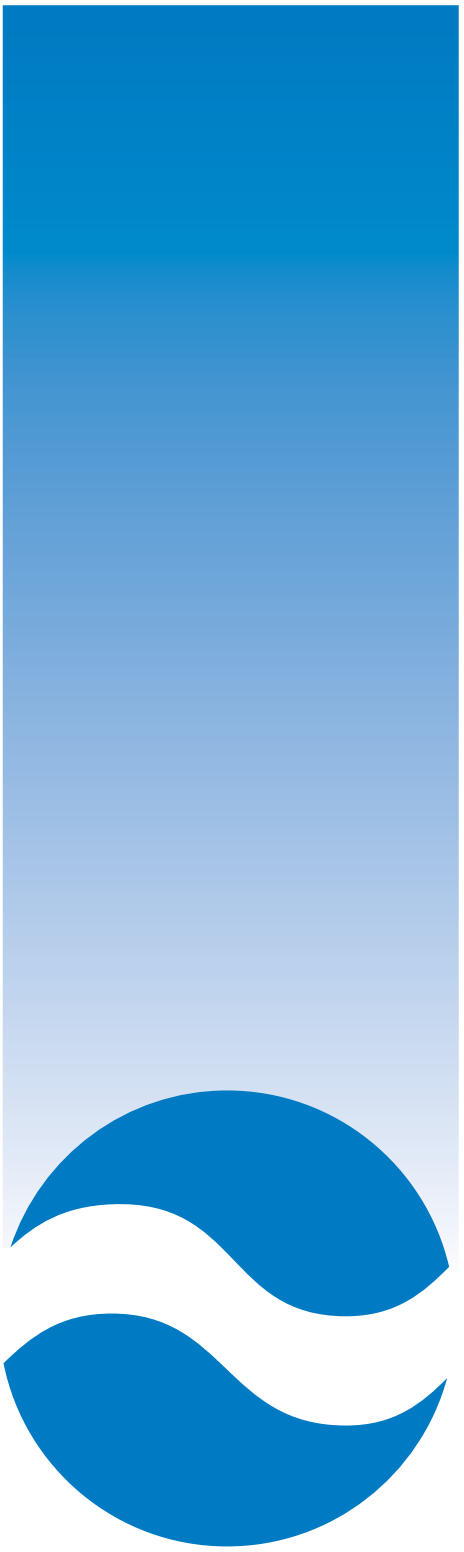
JOINT INDUSTRY STANDARD

Requirements for Soldered Electrical and Electronic Assemblies



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IPC J-STD-001E-2010

Requirements for Soldered Electrical and Electronic Assemblies

A joint standard developed by the IPC J-STD-001 development team including J-STD-001 Task Group (5-22a), J-STD-001 Task Group Asia (5-22aCN) and J-STD-001 Task Group Nordic (5-22aND) of the Assembly and Joining Processes Committees (5-20 and 5-20CN) of IPC

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Users of this publication are encouraged to participate in the development of future revisions.

Contact:
IPC
3000 Lakeside Drive, Suite 309S
Bannockburn, IL 60015-1249
Phone (847) 615-7100
Fax (847) 615-7105

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Army - AT
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Reviewer Activities:
Army - AV, MI

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Members of J-STD-001 Task Group (5-22a)

Arye Grushka, A. A. Training Consulting and Trade A.G. Ltd.
Teresa Rowe, AAI Corporation
Constantino Gonzalez, ACME Training & Consulting
Barry Morris, Advanced Rework Technology-A.R.T
Susan Morris, Advanced Rework Technology-A.R.T
Debbie Wade, Advanced Rework Technology-A.R.T
Russell Nowland, Alcatel-Lucent
Joseph Smetana, Alcatel-Lucent
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Glenn Dody, Dody Consulting
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Pam McCord, Elbit Systems of America
Yaakov Zissman, ELTA Systems Ltd.

Werner Engelmaier, Engelmaier Associates, L.C.
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Dewey Whittaker, Honeywell Inc. Air Transport Systems
William Novak, Honeywell International
Riley Northam, Honeywell Technology Solutions Inc.
Jennie Hwang, H-Technologies Group
Zhang Yuan, Huawei Technologies Co., Ltd.
Donald McFarland, Inovar, Inc.
Reza Ghaffarian, Jet Propulsion Laboratory
Alan Young, Jet Propulsion Laboratory
Joel Weiner, Johns Hopkins University
Akikazu Shibata, JPCA-Japan Electronics Packaging and Circuits Association
Nancy Bullock-Ludwig, Kimball Electronics Group
Norma Moss, L-3 Communications
Blen Talbot, L-3 Communications
Leopold Whiteman, L-3 Communications
Steven Nolan, Lockheed Martin Maritime Systems & Sensors
Dwayne Unglesbee, Lockheed Martin Maritime Systems & Sensors
Vijay Kumar, Lockheed Martin Missile & Fire Control
Linda Woody, Lockheed Martin Missile & Fire Control
Sam Polk, Lockheed Martin Missiles and Fire Control
Michael Green, Lockheed Martin Space Systems Company
Hue Green, Lockheed Martin Space Systems Company
David Ma, Lockheed Martin Space Systems Company
James Moffitt, Moffitt Consulting Services
Bill Kasprzak, Moog Inc.
Robert Humphrey, NASA Goddard Space Flight Center
Jeannette Plante, NASA Goddard Space Flight Center
Nick Virmani, NASA Goddard Space Flight Center
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Clarence Knapp, Northrop Grumman
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Mac Butler, Northrop Grumman Corporation
Tana Soffa, Northrop Grumman Corporation
Andrew Vilardo, Northrop Grumman Corporation
Alvin Luther, Northrop Grumman Laser Systems
William Rasmus, Northrop Grumman SSES
Kenneth Lee, NSWC - Corona Division
Peggi Blakley, NSWC Crane
Andrew Ganster, NSWC Crane
Gary Latta, NSWC Crane
William May, NSWC Crane
Eric Scott, NSWC Crane
Joseph Sherfick, NSWC Crane
Brian Langley, OK International
Ken Moore, Omni Training Corp.
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Matt Garrett, Phonon Corporation
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Gary Roper, Roper Resources, Inc.
Gaston Hidalgo, Samsung Telecommunications America
Donald Daebler, Sanmina-SCI
Dan Kelsey, Scienscope International Corporation
Finn Skaanning, Skaanning Quality & Certification-SQC
Terry Clitheroe, Solder Technologies
Frank Hules, Stellar Microelectronics Inc.
Mel Parrish, STI Electronics
Patricia Scott, STI Electronics
Tracy Clancy, Technical Training Center
Jennifer Day, U.S. Army Aviation & Missile Command
Sharon Ventress, U.S. Army Aviation & Missile Command
Constantin Hudon, Varitron Technologies Inc.
Denis Barbini, Vitronics Soltec
Lionel Fullwood, WKK Distribution Ltd.
Steven Sauer, Xetron Corp.

Members of the J-STD-001 Task Group (5-22aCN)

Zhang Yuan, Huawei Technologies Co., Ltd.
Liu Yunji, Huawei Technologies Co., Ltd.
He Dapeng, Huawei Technologies Co., Ltd.

Members of the J-STD-001 Task Group (5-22aND)

Turi Bach Roslund, Bang & Olufsen A/S
Keld Maaløe, BB Electronics A/S
Benny N. Nilsson, Ericsson AB
Oluf Richard Cramer, Flextronics A/S
Mona Johannesen, Flextronics A/S
Jesper Konge, Gåsdal Bygningsindustri A/S
Michael Lassen, Grundfos A/S
Palle Lund Pedersen, Grundfos A/S
Svein Kolbu, Hadeland Produkter
Jens Andersen, HYTEK
Alex Christensen, HYTEK
Christian Houmann, HYTEK
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Anny Benthe Emmerud, Kongsberg Defence & Aerospace AS
Gregers Dybdal, Linak A/S
Mari Pääkkönen, Nokia Siemens Networks Oy
Torgrim Nordhus, Norautron AS
Jens R. Gøttler, OJ Electronics A/S
Finn Skaanning, Skaanning Quality & Certification
Kai-Lykke Mathiasen, Styromatic A/S
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Michael Poulsen, Terma A/S
Torben Kruse, Vestas Control Systems A/S
Jan Vindvik, WesternGeco

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Requirements for Soldered Electrical and Electronic Assemblies

1 GENERAL

1.1 Scope This standard prescribes practices and requirements for the manufacture of soldered electrical and electronic assemblies. Historically, electronic assembly (soldering) standards contained a more comprehensive tutorial addressing principles and techniques. For a more complete understanding of this document's recommendations and requirements, one may use this document in conjunction with IPC-HDBK-001, IPC-A-610 and IPC-HDBK-610.

1.2 Purpose This standard describes materials, methods and acceptance criteria for producing soldered electrical and electronic assemblies. The intent of this document is to rely on process control methodology to ensure consistent quality levels during the manufacture of products. It is not the intent of this standard to exclude any procedure for component placement or for applying flux and solder used to make the electrical connection.

1.3 Classification This standard recognizes that electrical and electronic assemblies are subject to classifications by intended end-item use. Three general end-product classes have been established to reflect differences in producibility, complexity, functional performance requirements, and verification (inspection/test) frequency. It should be recognized that there may be overlaps of equipment between classes.

The user (see 1.8.13) is responsible for defining the product class. The product class should be stated in the procurement documentation package.

CLASS 1 General Electronic Products
Includes products suitable for applications where the major requirement is function of the completed assembly.

CLASS 2 Dedicated Service Electronic Products
Includes products where continued performance and extended life is required, and for which uninterrupted service is desired but not critical. Typically the end-use environment would not cause failures.

CLASS 3 High Performance Electronic Products
Includes products where continued high performance or performance-on-demand is critical, equipment downtime cannot be tolerated, end-use environment may be uncommonly harsh, and the equipment must function when required, such as life support or other critical systems.

1.4 Measurement Units and Applications All dimensions and tolerances, as well as other forms of measurement (temperature, weight, etc.) in this standard are expressed in SI (System International) units (with Imperial English equivalent dimensions provided in brackets). Dimensions and tolerances use millimeters as the main form of dimensional expression; micrometers are used when the precision required makes millimeters too cumbersome. Celsius is used to express temperature. Weight is expressed in grams.

1.4.1 Verification of Dimensions Actual measurement of specific part mounting and solder fillet dimensions and determination of percentages are not required except for referee purposes. For the purposes of determining conformance to this specification, all specified limits in this standard are absolute limits as defined in ASTM E29.